

# DATA SHEET

**74ABT861**

**10-bit bus transceiver (3-State)**

Product specification  
Supersedes data of 1995 Sep 06  
IC23 Data Handbook

1998 Jan 16

# 10-bit bus transceiver (3-State)

# 74ABT861

## FEATURES

- Provides high performance bus interface buffering for wide data/address paths or buses carrying parity
- Buffered control inputs for light loading, or increased fan-in as required with MOS microprocessors
- Output capability: +64mA/-32mA
- Latch-up protection exceeds 500mA per Jedec Std 17
- ESD protection exceeds 2000 V per MIL STD 883 Method 3015 and 200 V per Machine Model
- Power-up 3-State
- Inputs are disabled during 3-State mode

## DESCRIPTION

The 74ABT861 bus transceiver provides high performance bus interface buffering for wide data/address paths of buses carrying parity.

The 74ABT861 10-bit bus transceiver has NOR-ed transmit and receive output enables for maximum control flexibility.

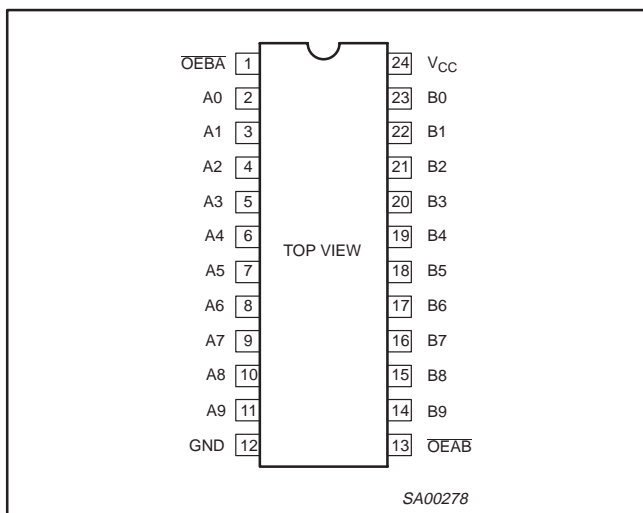
## QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS $T_{amb} = 25^{\circ}C; GND = 0V$	TYPICAL	UNIT
$t_{PLH}$ $t_{PHL}$	Propagation delay An to Bn or Bn to An	$C_L = 50pF; V_{CC} = 5V$	3.4	ns
$C_{IN}$	Input capacitance	$V_I = 0V$ or $V_{CC}$	4	pF
$C_{I/O}$	I/O capacitance	Outputs disabled; $V_O = 0V$ or $V_{CC}$	7	pF
$I_{CCZ}$	Total supply current	Outputs disabled; $V_{CC} = 5.5V$	500	nA

## ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
24-Pin Plastic DIP	-40°C to +85°C	74ABT861 N	74ABT861 N	SOT222-1
24-Pin plastic SO	-40°C to +85°C	74ABT861 D	74ABT861 D	SOT137-1
24-Pin Plastic SSOP Type II	-40°C to +85°C	74ABT861 DB	74ABT861 DB	SOT340-1
24-Pin Plastic TSSOP Type I	-40°C to +85°C	74ABT861 PW	74ABT861PW DH	SOT355-1

## PIN CONFIGURATION



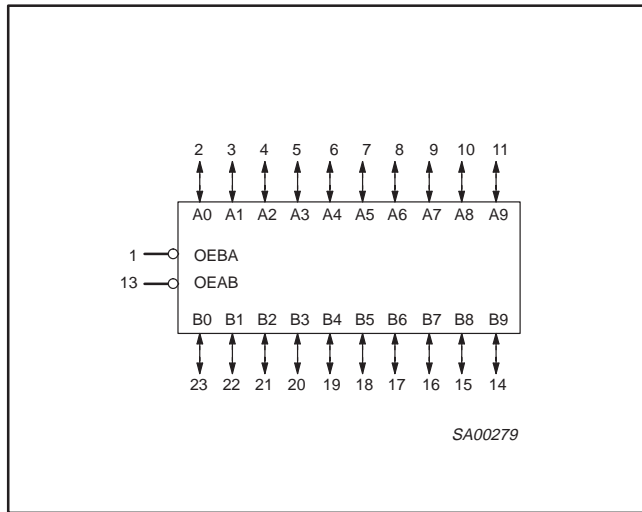
## PIN DESCRIPTION

PIN NUMBER	SYMBOL	FUNCTION
13	$\overline{OEAB}$	A side to B side output enable input (active-Low)
2, 3, 4, 5, 6, 7, 8, 9, 10, 11	A0-A9	Data inputs/outputs (A side)
23, 22, 21, 20, 19, 18, 17, 16, 15, 14	B0-B9	Data inputs/outputs (B side)
1	$\overline{OEBA}$	B side to A side output enable input (active-Low)
12	GND	Ground (0V)
24	$V_{CC}$	Positive supply voltage

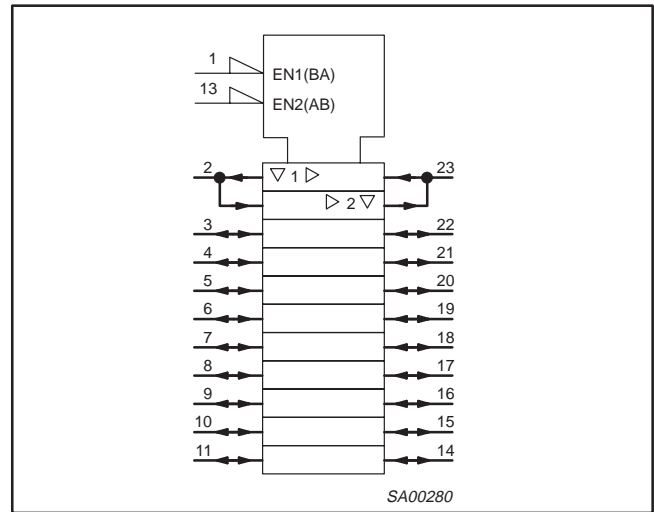
# 10-bit bus transceiver (3-State)

# 74ABT861

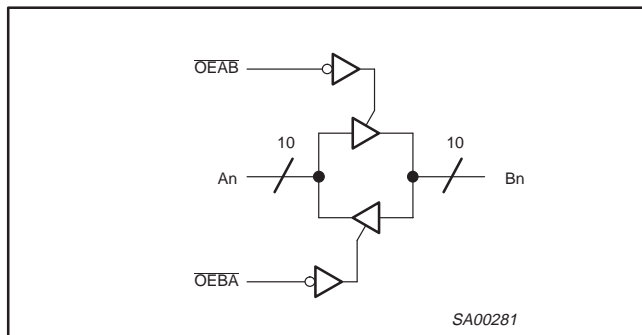
## LOGIC SYMBOL



## LOGIC SYMBOL (IEEE/IEC)



## LOGIC DIAGRAM



## FUNCTION TABLE

INPUTS		OPERATING MODE
OEAB	OEBA	
L	H	A data to B bus
H	L	B data to A bus
H	H	Z

H = High voltage level  
 L = Low voltage level  
 X = Don't care  
 Z = High impedance "off" state

## ABSOLUTE MAXIMUM RATINGS<sup>1, 2</sup>

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
$V_{CC}$	DC supply voltage		-0.5 to +7.0	V
$I_{IK}$	DC input diode current	$V_I < 0$	-18	mA
$V_I$	DC input voltage <sup>3</sup>		-1.2 to +7.0	V
$I_{OK}$	DC output diode current	$V_O < 0$	-50	mA
$V_{OUT}$	DC output voltage <sup>3</sup>	output in Off or High state	-0.5 to +5.5	V
$I_{OUT}$	DC output current	output in Low state	128	mA
$T_{stg}$	Storage temperature range		-65 to 150	°C

### NOTES:

- Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.
- The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

## 10-bit bus transceiver (3-State)

74ABT861

## RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIMITS		UNIT
		Min	Max	
V <sub>CC</sub>	DC supply voltage	4.5	5.5	V
V <sub>I</sub>	Input voltage	0	V <sub>CC</sub>	V
V <sub>IH</sub>	High-level input voltage	2.0		V
V <sub>IL</sub>	Low-level input voltage		0.8	V
I <sub>OH</sub>	High-level output current		-32	mA
I <sub>OL</sub>	Low-level output current		64	mA
Δt/Δv	Input transition rise or fall rate	0	5	ns/V
T <sub>amb</sub>	Operating free-air temperature range	-40	+85	°C

## DC ELECTRICAL CHARACTERISTICS

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS					UNIT
			T <sub>amb</sub> = +25°C			T <sub>amb</sub> = -40°C to +85°C		
			Min	Typ	Max	Min	Max	
V <sub>IK</sub>	Input clamp voltage	V <sub>CC</sub> = 4.5V; I <sub>IK</sub> = -18mA		-0.9	-1.2		-1.2	V
V <sub>OH</sub>	High-level output voltage	V <sub>CC</sub> = 4.5V; I <sub>OH</sub> = -3mA; V <sub>I</sub> = V <sub>IL</sub> or V <sub>IH</sub>	2.5	3.5		2.5		V
		V <sub>CC</sub> = 5.0V; I <sub>OH</sub> = -3mA; V <sub>I</sub> = V <sub>IL</sub> or V <sub>IH</sub>	3.0	4.0		3.0		V
		V <sub>CC</sub> = 4.5V; I <sub>OH</sub> = -32mA; V <sub>I</sub> = V <sub>IL</sub> or V <sub>IH</sub>	2.0	2.6		2.0		V
V <sub>OL</sub>	Low-level output voltage	V <sub>CC</sub> = 4.5V; I <sub>OL</sub> = 64mA; V <sub>I</sub> = V <sub>IL</sub> or V <sub>IH</sub>		0.42	0.55		0.55	V
I <sub>I</sub>	Input leakage current	Control pins V <sub>CC</sub> = 5.5V; V <sub>I</sub> = GND or 5.5V		±0.01	±1.0		±1.0	μA
		Data pins V <sub>CC</sub> = 5.5V; V <sub>I</sub> = GND or 5.5V		±5.0	±100		±100	μA
I <sub>OFF</sub>	Power-off leakage current	V <sub>CC</sub> = 0.0V; V <sub>O</sub> or V <sub>I</sub> ≤ 4.5V		±5.0	±100		±100	μA
I <sub>PU/PD</sub>	Power-up/down 3-State output current <sup>3</sup>	V <sub>CC</sub> = 2.1V; V <sub>O</sub> = 0.5V; V <sub>I</sub> = GND or V <sub>CC</sub> ; V <sub>OE</sub> = V <sub>CC</sub>		±5.0	±50		±50	μA
I <sub>IH</sub> + I <sub>OZH</sub>	3-State output High current	V <sub>CC</sub> = 5.5V; V <sub>O</sub> = 2.7V; V <sub>I</sub> = V <sub>IL</sub> or V <sub>IH</sub>		5.0	50		50	μA
I <sub>IL</sub> + I <sub>OZL</sub>	3-State output Low current	V <sub>CC</sub> = 5.5V; V <sub>O</sub> = 0.5V; V <sub>I</sub> = V <sub>IL</sub> or V <sub>IH</sub>		-5.0	-50		-50	μA
I <sub>CEx</sub>	Output high leakage current	V <sub>CC</sub> = 5.5V; V <sub>O</sub> = 5.5V; V <sub>I</sub> = GND or V <sub>CC</sub>		5.0	50		50	μA
I <sub>O</sub>	Output current <sup>1</sup>	V <sub>CC</sub> = 5.5V; V <sub>O</sub> = 2.5V	-50	-100	-180	-50	-180	mA
I <sub>CCH</sub>	Quiescent supply current	V <sub>CC</sub> = 5.5V; Outputs High, V <sub>I</sub> = GND or V <sub>CC</sub>		0.5	250		250	μA
I <sub>CCL</sub>		V <sub>CC</sub> = 5.5V; Outputs Low, V <sub>I</sub> = GND or V <sub>CC</sub>		25	38		38	mA
I <sub>CCZ</sub>		V <sub>CC</sub> = 5.5V; Outputs 3-State; V <sub>I</sub> = GND or V <sub>CC</sub>		0.5	50		50	μA
ΔI <sub>CC</sub>	Additional supply current per input pin <sup>2</sup>	Outputs enabled, one input at 3.4V, other inputs at V <sub>CC</sub> or GND; V <sub>CC</sub> = 5.5V		0.5	1.5		1.5	mA
		Outputs 3-State, one data input at 3.4V, other inputs at V <sub>CC</sub> or GND; V <sub>CC</sub> = 5.5V		0.01	50		50	μA
		Outputs 3-State, one enable input at 3.4V, other inputs at V <sub>CC</sub> or GND; V <sub>CC</sub> = 5.5V		0.5	1.5		1.5	mA

## NOTES:

- Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
- This is the increase in supply current for each input at 3.4V.
- This parameter is valid for any V<sub>CC</sub> between 0V and 2.1V with a transition time of up to 10msec. For V<sub>CC</sub> = 2.1V to V<sub>CC</sub> = 5V ± 10%, a transition time of up to 100μsec is permitted.

# 10-bit bus transceiver (3-State)

# 74ABT861

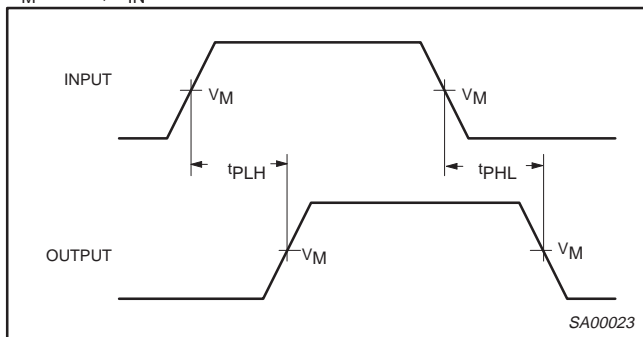
## AC CHARACTERISTICS

GND = 0V,  $t_R = t_F = 2.5\text{ns}$ ,  $C_L = 50\text{pF}$ ,  $R_L = 500\Omega$

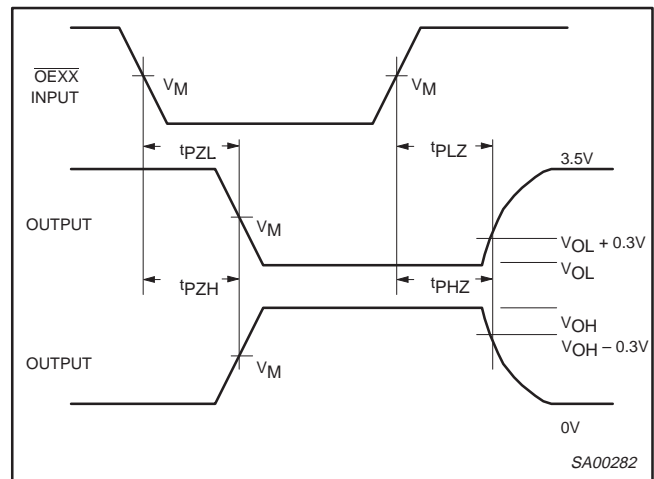
SYMBOL	PARAMETER	WAVEFORM	LIMITS					UNIT
			$T_{\text{amb}} = +25^\circ\text{C}$ $V_{\text{CC}} = +5.0\text{V}$			$T_{\text{amb}} = -40 \text{ to } +85^\circ\text{C}$ $V_{\text{CC}} = +5.0\text{V} \pm 0.5\text{V}$		
			Min	Typ	Max	Min	Max	
$t_{\text{PLH}}$ $t_{\text{PHL}}$	Propagation delay An to Bn or Bn to An	1	1.1 1.0	3.4 3.2	4.9 4.9	1.1 1.0	5.2 5.2	ns
$t_{\text{PZH}}$ $t_{\text{PZL}}$	Output enable time to High and Low level	2	1.2 2.4	3.5 4.6	5.0 6.0	1.2 2.4	5.9 6.9	ns
$t_{\text{PHZ}}$ $t_{\text{PLZ}}$	Output disable time from High and Low level	2	3.1 3.7	5.3 5.3	6.5 6.6	3.1 3.7	7.5 7.1	ns

## AC WAVEFORMS

$V_M = 1.5\text{V}$ ,  $V_{\text{IN}} = \text{GND to } 3.0\text{V}$

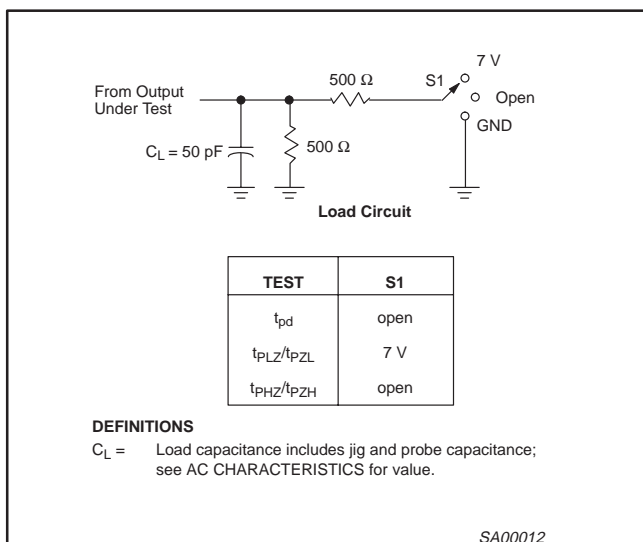


Waveform 1. Input to Output Propagation Delays



Waveform 2. 3-State Output Enable and Disable Times

## TEST CIRCUIT AND WAVEFORM

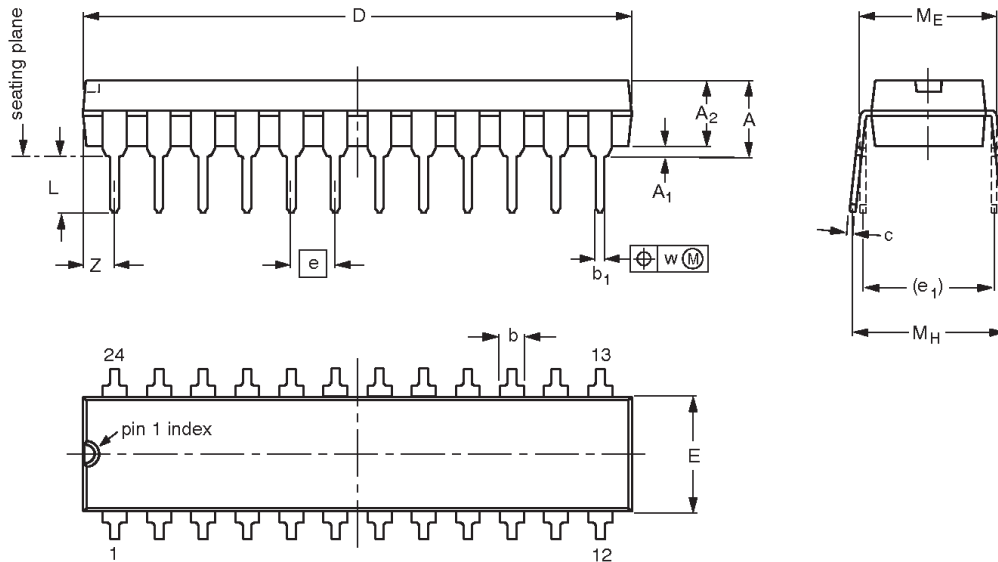


# 10-bit bus transceiver (3-State)

# 74ABT861

DIP24: plastic dual in-line package; 24 leads (300 mil)

SOT222-1



**DIMENSIONS (millimetre dimensions are derived from the original inch dimensions)**

UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	e <sub>1</sub>	L	M <sub>E</sub>	M <sub>H</sub>	w	Z <sup>(1)</sup> max.
mm	4.70	0.38	3.94	1.63 1.14	0.56 0.43	0.36 0.25	31.9 31.5	6.73 6.48	2.54	7.62	3.51 3.05	8.13 7.62	10.03 7.62	0.25	2.05
inches	0.185	0.015	0.155	0.064 0.045	0.022 0.017	0.014 0.010	1.256 1.240	0.265 0.255	0.100	0.300	0.138 0.120	0.32 0.30	0.395 0.300	0.01	0.081

**Note**

1. Plastic or metal protrusions of 0.01 inches maximum per side are not included.

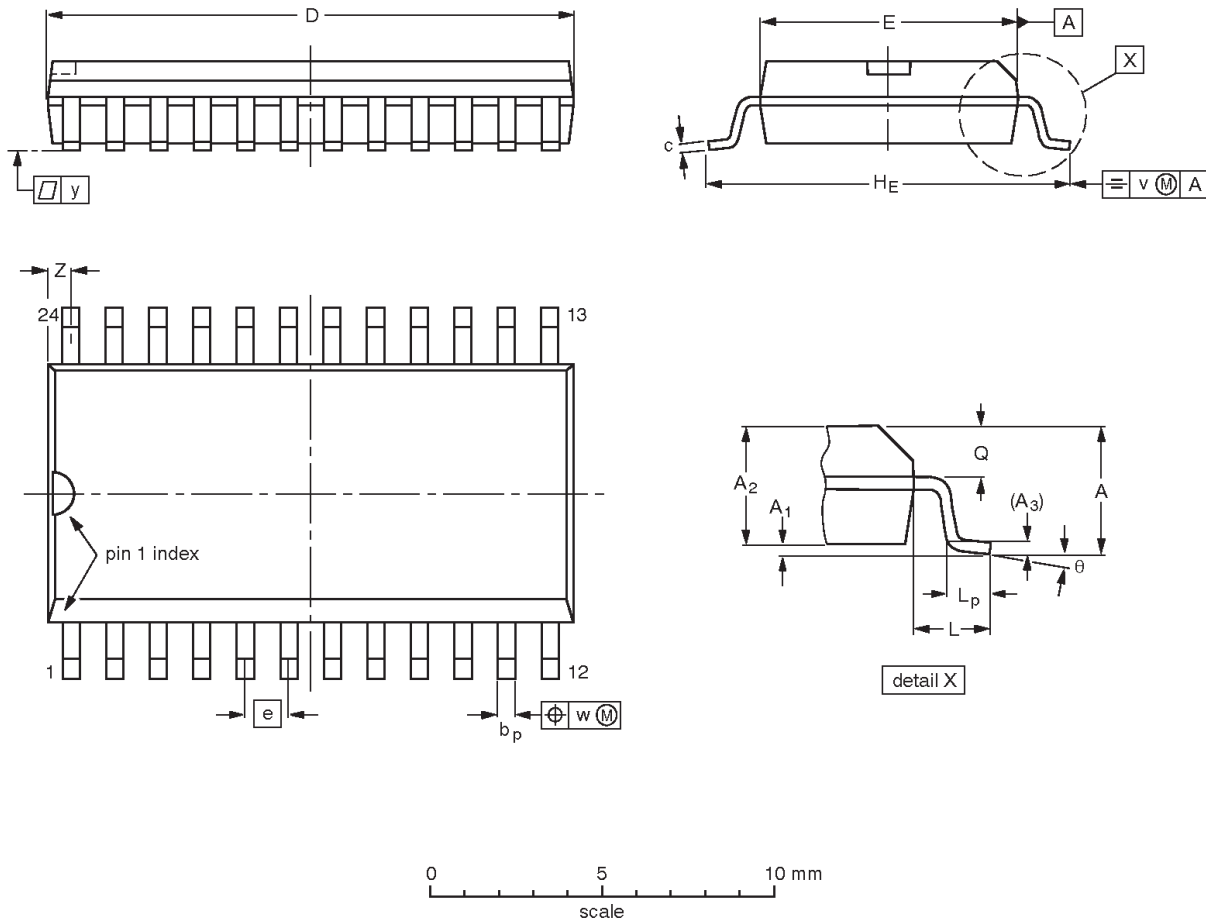
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT222-1		MS-001AF				95-03-11

# 10-bit bus transceiver (3-State)

# 74ABT861

**SO24: plastic small outline package; 24 leads; body width 7.5 mm**

**SOT137-1**



**DIMENSIONS (inch dimensions are derived from the original mm dimensions)**

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	z <sup>(1)</sup>	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	15.6 15.2	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8° 0°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.61 0.60	0.30 0.29	0.050	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

**Note**

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

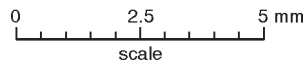
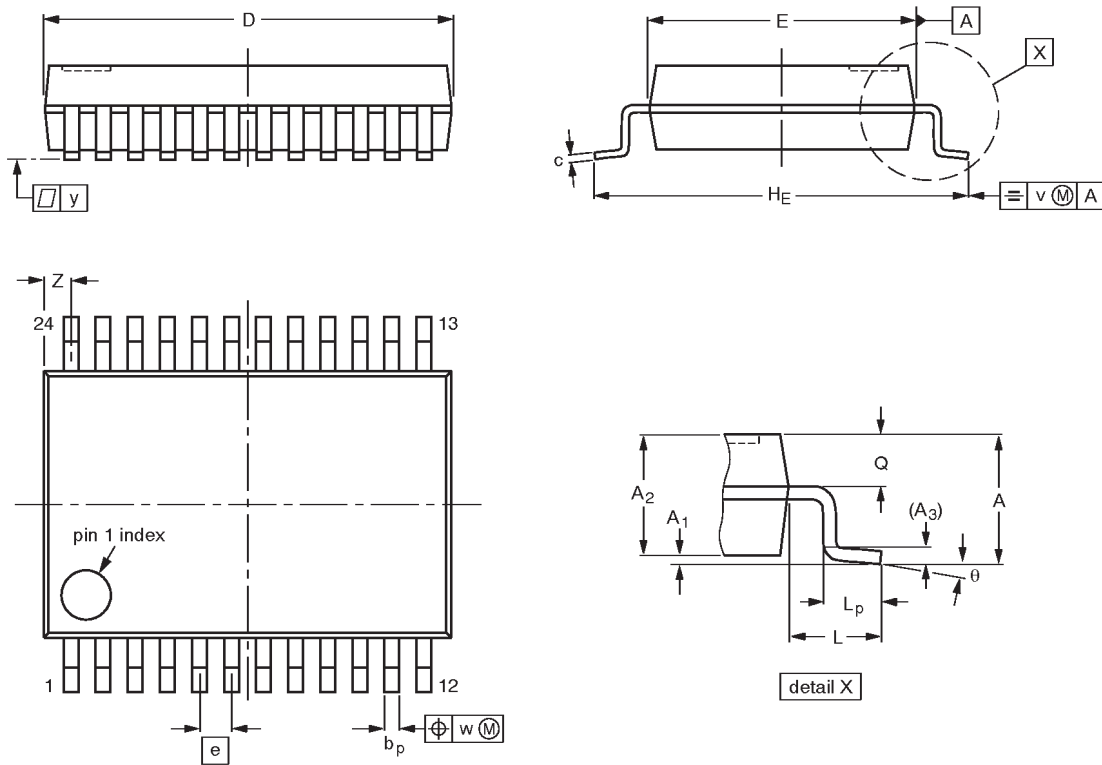
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT137-1	075E05	MS-013AD				95-01-24 97-05-22

10-bit bus transceiver (3-State)

74ABT861

SSOP24: plastic shrink small outline package; 24 leads; body width 5.3 mm

SOT340-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	8.4 8.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.8 0.4	8° 0°

Note

1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT340-1		MO-150AG				93-09-08- 95-02-04

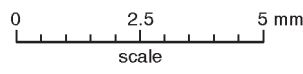
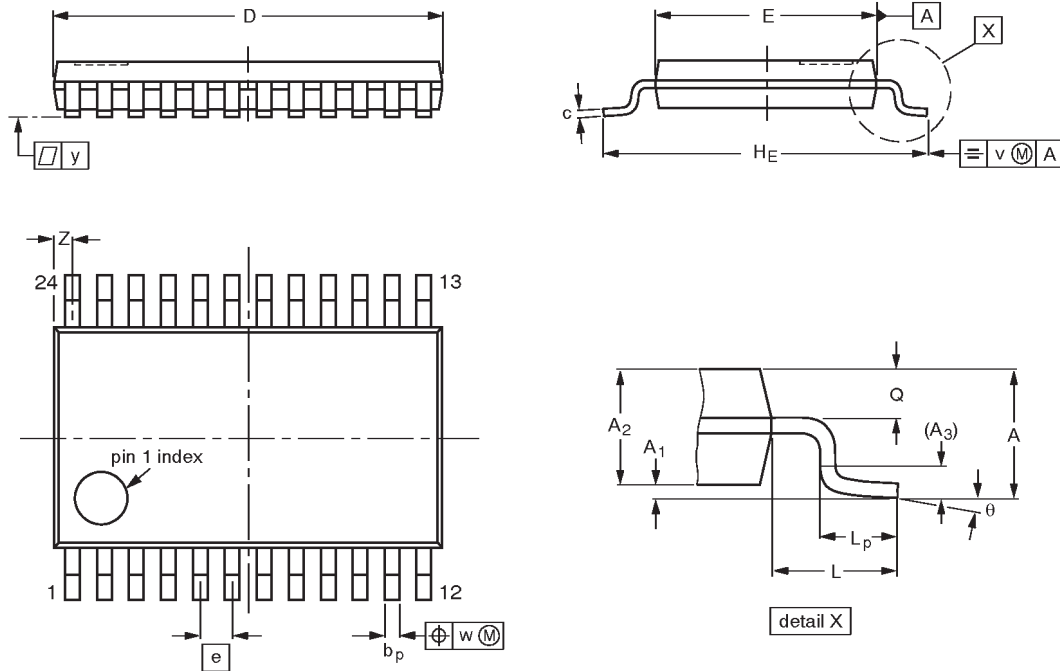


10-bit bus transceiver (3-State)

74ABT861

TSSOP24: plastic thin shrink small outline package; 24 leads; body width 4.4 mm

SOT355-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(2)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	7.9 7.7	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT355-1		MO-153AD				93-06-16 95-02-04

## 10-bit bus transceiver (3-State)

74ABT861

## Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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[1] Please consult the most recently issued datasheet before initiating or completing a design.

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**Limiting values definition** — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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print code

Date of release: 05-96

Document order number:

9397-750-03476

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